European Network on New Sensing Technologies for Air Pollution Control and Environmental Sustainability - *EuNetAir*

COST Action TD1105

4th International Workshop *EuNetAir* on *Innovations and Challenges for Air Quality Control Sensors* FFG - Austrian Research Promotion Agency - Austrian COST Association Vienna, Austria, 25 - 26 February 2016

"Environmental Sensors and Miniaturization"



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ESF provides the COST Office

About ams

Shaping the world with sensor solutions

Focus

- Designing and manufacturing advanced
 analog sensor solutions
- Markets: communications, consumer, industrial, automotive and medical
- Solutions: intelligent light sensors, CIS, RFID/NFC, chemical sensors, active-noisecancelling ICs, position sensors, ultra-low power management, and more
- Standard products & custom solutions (ASICs & foundry services)

People:

- More than 2,100 employees in 20 countries
- 18 design centers
- 20 sales offices
- 30+ channel partners

Manufacturing

- IDM with 30+ years of experience
- Advanced processes: CMOS, HV-CMOS and SiGe, 3D TSV
- Certified for automotive & medical production
- Full service foundry including packaging and testing options
- 8 inch wafer fab in Austria (180k wspa)
- Test facility in Calamba, Philippines
- Strong relationships with global manufacturing partners

Financials

- Revenues 2015 EUR623m/\$691m (2014: EUR 464m/\$614m)
- Revenues Q4 2015 EUR147m/\$161m (Q4 2014: EUR139m/\$141m)

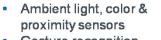
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The world of sensors

Smart Phones & Tablet



Wearables



- Gesture recognition
- NFC-based contactless payment solutions
- Environmental sensors
- Active Noise Cancellation
- Spectral sensors
- Biosensors, heart rate monitoring
- Power management
 NFC-based contactless payment solutions
- Active Noise Cancellation
- Environmental sensors

Smart Home & Buildings



- Gas sensors
- Temperature sensors
- Smart light sensors
- Humidity sensors
- Pressure sensors
- Flow sensors
- Lightning sensors

- Position sensors
- Sensors for advanced
 driver assistance
- Air quality sensors
- Hydrogen sensors



Industrial

Automotive

- Position sensors
- CMOS sensors for machine vision and drones
- Industrial/building automation
- Flow sensors (Heat, Water, Gas Metering)
- NFC Sensor Tags
- Image Sensors for:
 - Computed tomography
 - Digital x-ray
 - Ultrasound
 - Surgical robots
- CMOS image sensors for endoscopy (miniature cameras)



Medical



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Overview

- 1. Sensors and Smart Systems
- 2. Environmental Sensor Market Needs and Applications
- 3. Environmental Sensors and Technologies
- 4. Miniaturization
- 5. Conclusions

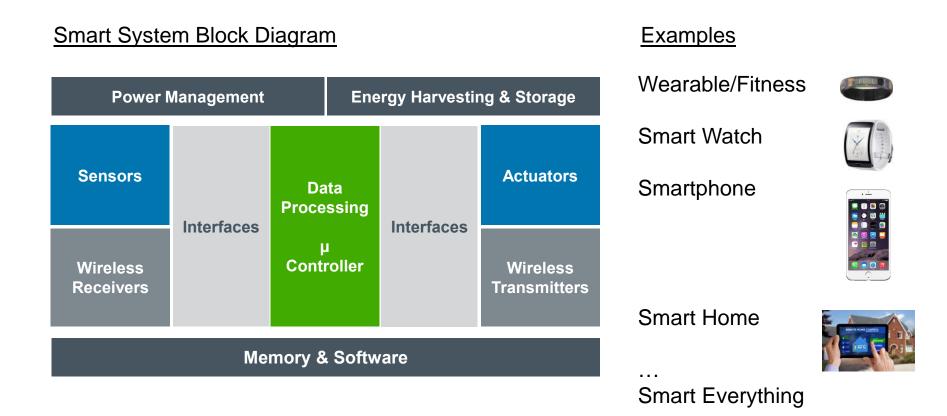




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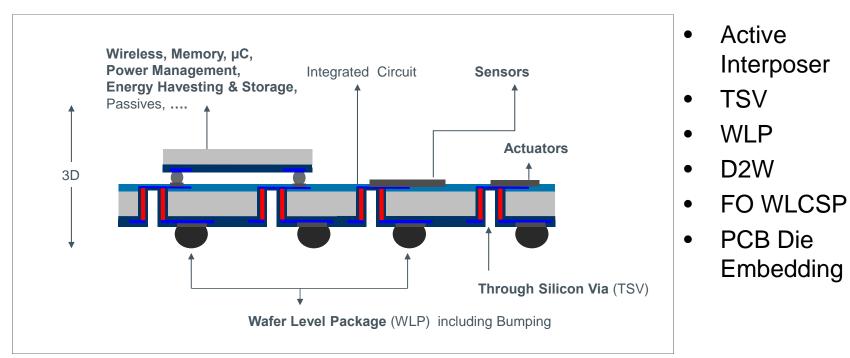


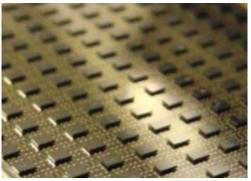
Smart Systems

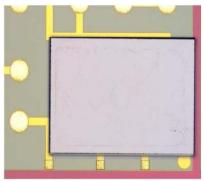




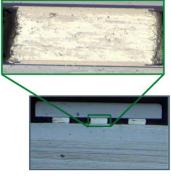
Miniaturized Smart Systems









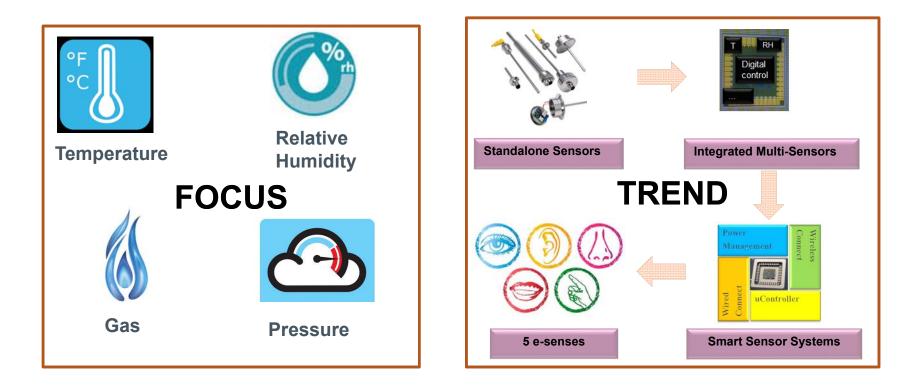


Source: F.Schrank et al. (2015)

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Environmental Sensors

- Provide environmental information to people
- > EM radiation, sound, pressure, temperature, gas, particles





Overview

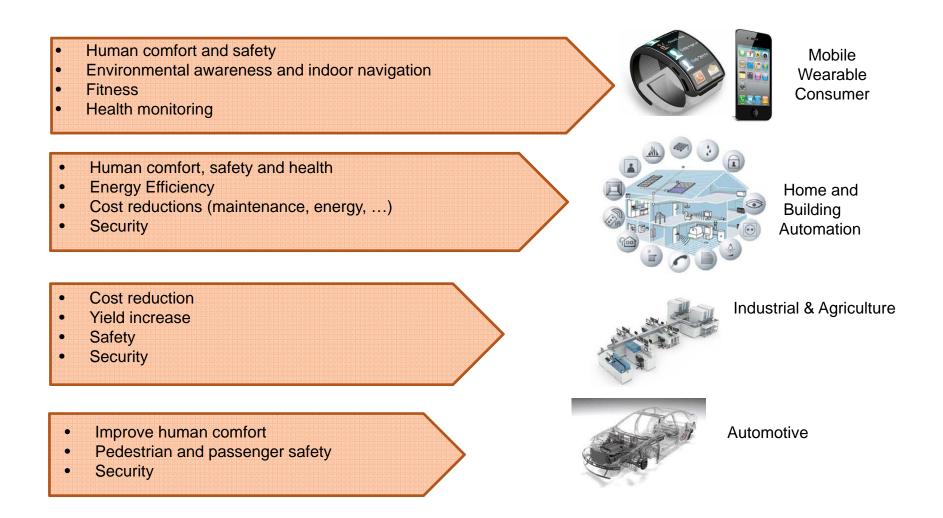
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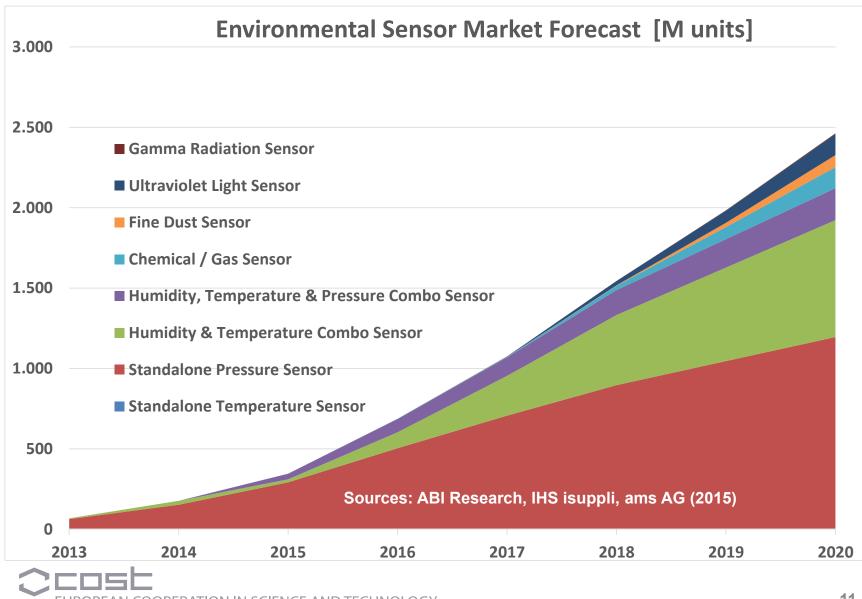


Market Drivers



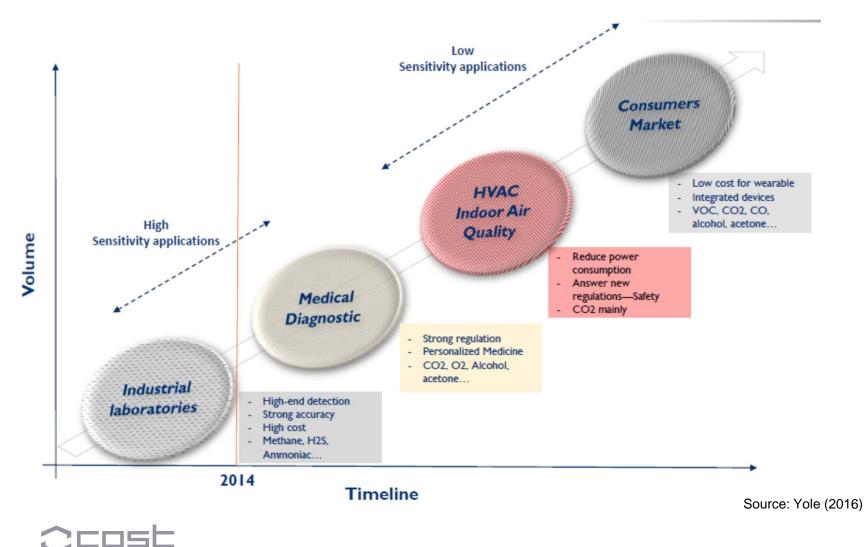


Environmental Sensor Market



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Gas Sensor Applications



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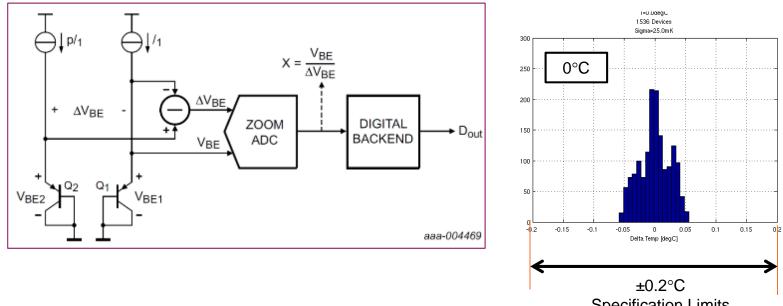
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Temperature

CMOS-based design block (Bandgap)



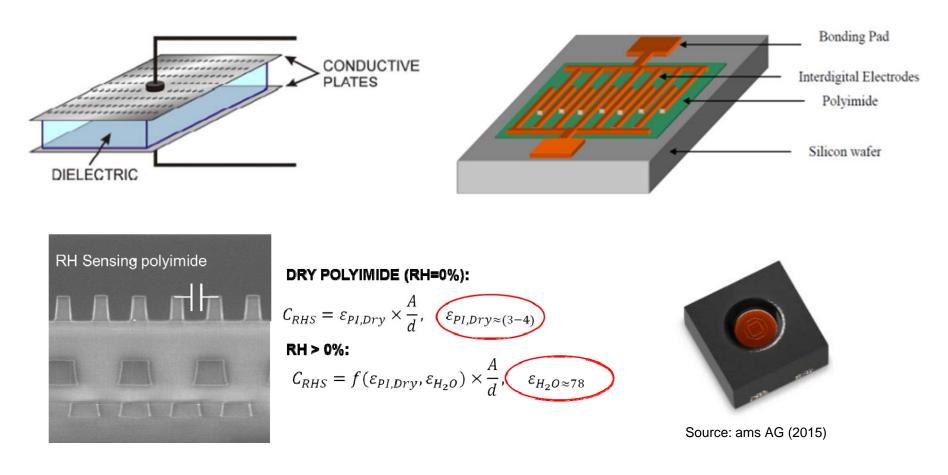
Specification Limits

Source: ams AG (2015)

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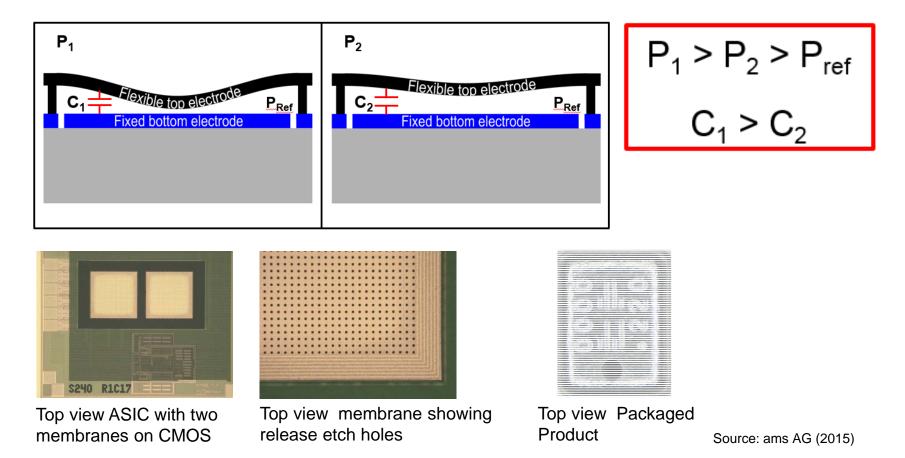
Humidity

• SoC integrated humidity sensor (CMOS postprocessing)

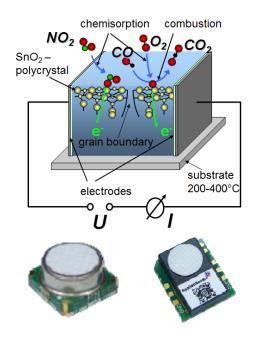


Pressure

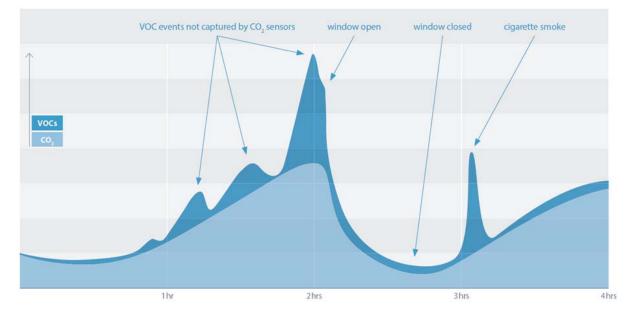
• SoC integrated pressure sensor (CMOS postprocessing)



Volatile Organic Compounds



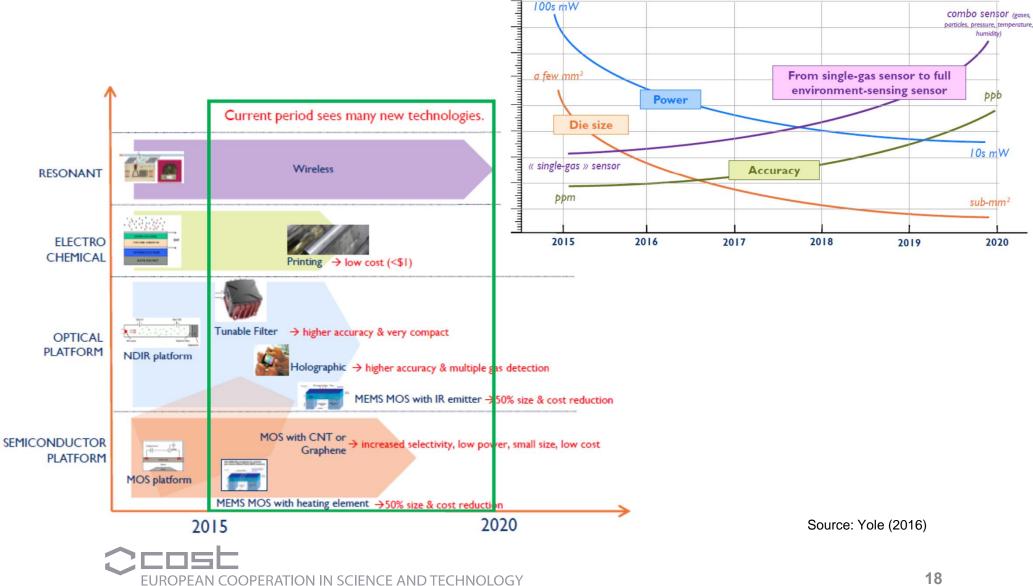
CO, and VOCs from business meeting session



Source: ams AG (2015)



Gas Sensor Trends



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Gas Sensor Technologies

| Gas sensing technologies | Principles | Chip size | Power consumption | ASP |
|-----------------------------|---|--|--|---|
| NDIR | IR light passes through the gas & an IR detector measures the transmitting light (MWIR is used to detect CO and CO2) | • ~ cm² range | 100s mW for pyro (3.5 mW for COZIR from GSS) 50µW with PD | For CO2 HVAC: \$30- \$80 Target ASP for wearable applications: \$2-\$3 |
| FTIR | An FTIR spectrometer simultaneously collects high spectral resolution data over a wide spectral range (different of NDIR which has narrow range of wavelengths). | • many cm ² | • 150–300 W | • \$1000s |
| Holographic | Uses a DOE with gratings, lens, splitters for higher accuracy & multiple gas detection (Optosense) | ~ 10x10 mm² | • mW | • \$100-\$500 |
| Electrochemical | Electrochemical reaction between sensing & counter electrodes creates a current proportional to target gas concentration | • ~ 20 mm² | 100s µW range | • \$20 |
| Printed electrochemical | Same as above but using screen printing technology | • 15x15x3 mm ³ | Zero (based on energy harvesting) | • <\$1 target |
| MOS | Gas absorption at the surface of heated oxide (200–250°C) that results in change of electrical resistance related to sample gas concentration | • 3.2 x 2.5 x 0.99 (mm3) | I-10s of mWs range | \$2 for very high volume to \$60 for industrial applications MEMS technology could achieved \$0.20 (SGX) |

Source: Yole (2016)



Gas Sensor Technologies contd.

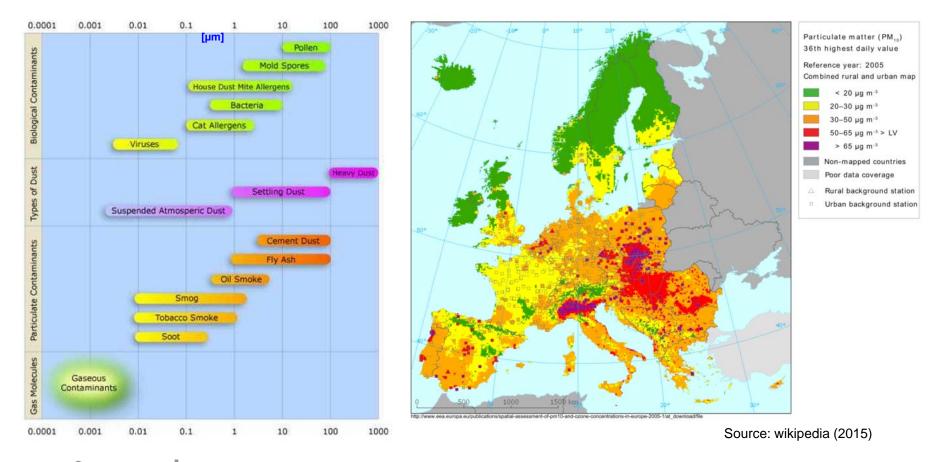
| Gas sensing technologies | Principles | Chip size | Power consumptio n | ASP |
|-----------------------------|--|--|--|---|
| Catalytic/Pellistor | Resistance change through the increase of temperature of a Pt wire impregnated with a catalyst (thus promoting oxidation) compared to a second Pt wire with no oxidation. | • ~ 1mm long | 10–100s mW range | • \$40–\$60 (SGX) |
| Acoustic/Photo- acoustic | Photoacoustic spectroscopy is the measurement of the effect of absorbed light by means of acoustic detection. The absorption depends on the wavelength. A microphone is used for detection. | • ~cm ² range | • W range | • >\$1500 |
| ChemFET | Structure is similar to a MOSFET with an electrode replaced by a chemically sensitive membrane. There is NO heating compared to MOSFET. | • ~mm² | 10s of mW range | • Est < \$10 |
| Resonant | Quartz resonators sensitive to adsorbed gas species | A few mm ² | • Low (few mW) | Est a few \$ (a SAW filter is \$0.10-\$0.25) |
| PID / GC | Photo-ionization (e.g., UV) breaks molecules into positive ions. The gas becomes electrically charged and the ions produce an electric current, which is the signal output of the detector. | Miniaturized system: 1 liter size (APIX) | 1000W (lab tool) | From \$50k (3 gases) to \$150k (13 gases) Portable system cost: a few \$100s is targeted |
| Chemiluminescence | Emission of light as the result of a chemical reaction. | Not miniaturized | • 100s W | • \$10k to \$15k |

Source: Yole (2016)



Fine Dust

• Fine Particles (< 2.5μm, < 10μm) pose health hazards (cancer,..)



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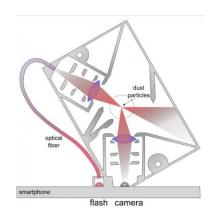
Fine Dust Sensors

Optical ~ m³



Fine Dust Measurement Station

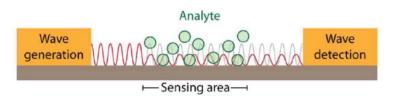
Optical ~ cm³



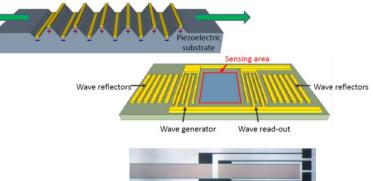


Optical Fine Dust measurement using Mobile phone functions (Budde et al. (2013))

MEMS $\sim mm^3$



Film Bulk Acoustic wave Resonator (FBAR)





Fine Dust measurement e.g. by SAW / FBAR (S.Thomas et al. (2013))



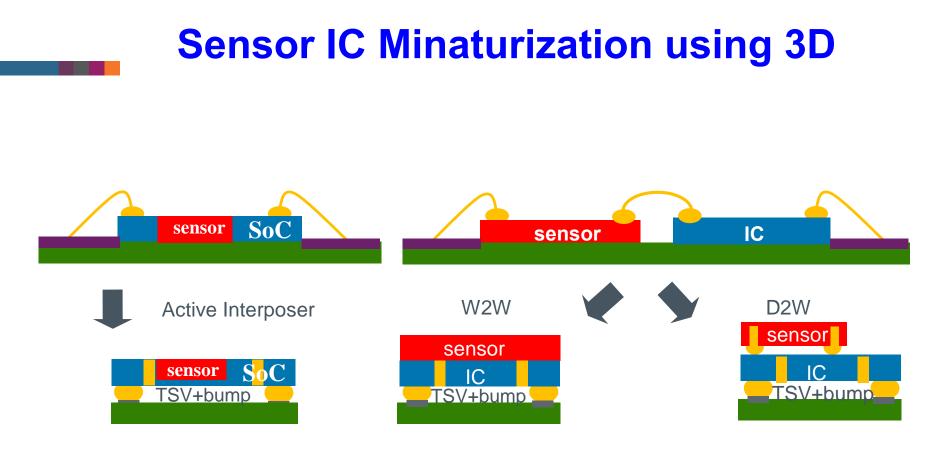
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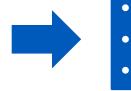
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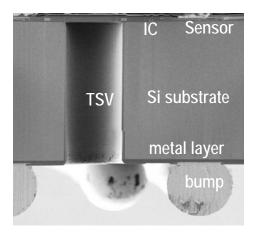


- System on Chip (SoC) with TSV and RDL
- Wafer to Wafer (W2W) bonding for matched sensor and IC die sizes
- Die to Wafer (D2W) bonding if sensor and IC die sizes do not match

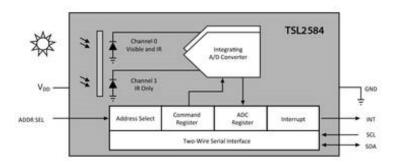


- Form factor reduction
- System cost reduction
- Better performance

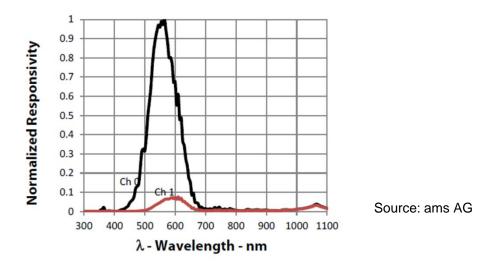
Light Sensor with 3D/TSV



- World's smallest Ambient Light Sensor
- Using 3D/TSV
- Height of only 0.218mm w/o bumps



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| Benefits | Features |
|--|--|
| Approximates Human Eye Response | Dual Diode with Photopic Filter |
| Flexible Operation | Programmable Analog Gain and Integration Time |
| Suited for Operation Behind Dark Glass | • 1,000,000: 1 Dynamic Range |
| Low Operating Overhead | Programmable Upper and Lower Thresholds Programmable Persistence Filter |
| Low Power | 3.0 μA Sleep State |
| Industry Standard Two-Wire Interface | I²C Fast Mode Compatible Interface Data Rates up to 400 kbit/s Input Voltage Levels Compatible with 1.8–V Bus |
| Ultra-Small Foot-Print | 1.145 mm x 1.660 mm TSV (Through Silicon Via) 0.218 mm Height w/o Solder Balls |
| Unlimited Manufacturing Floor Life | MSL1 Rated |

3D Gas Sensor IC

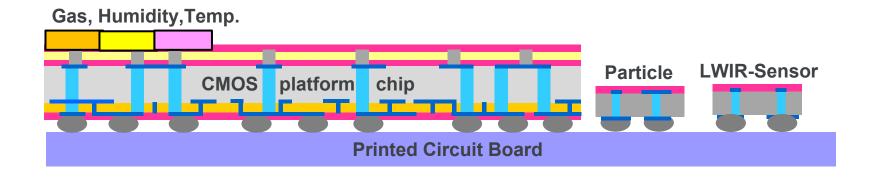
System on Chip (SoC) integration with 3D/TSV circuitry poly-silicon heater power consumption 9 mW μΗΡ 400 TSVs 300 7 [°C] ture 200 28 10 15 Electrical power Pel [mW] ╗<mark>╷╔╷╔_┪╔╶╓</mark>╔┍╝ THE eadou µ hotplate CMOS µ hotplate temp. control **TSVs**

Source: A.Nemecek et al., Semicon Europe (2014) ; ams AG

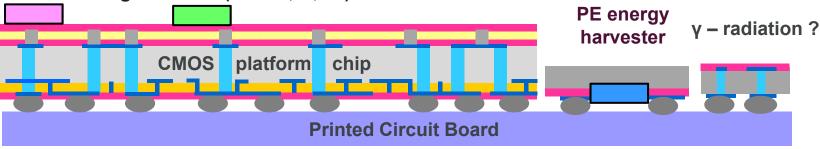


EU project "Multi-Sensor Platform"

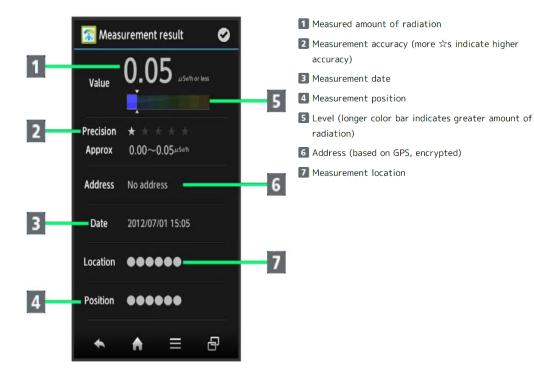
• Ambition: Integration of multiple sensor functions



T- Sensor Light Sensor (RGBW,IR,UV)



Gamma Radiation



Sharp Pantone 5 107SH 0.05µSv/h (min) (dedicated semiconductor sensors 2x100mm2) Source: Sharp (2012)

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iPhone 4s using camera covered with black tape & SW app 1µSv/h (min) Source: ansto (2014)

CONCLUSIONS

- Sensors for environmental parameters such as gas, humidity, temperature and pressure as well as EM radiation have become available with increasingly smaller form factors.
- Chemical and fine dust sensing are particular areas where further R&D is needed for identifying the optimum sensing technologies with respect to sensitivity, size and cost.
- Cost reduction and the use of small form factor mobile devices drive the further miniaturization of sensors and electronics as well as the combination of multiple sensor functions
- Miniaturization is enabled by recently developed Wafer Level Packaging and 3D integration technologies with Through Silicon Vias and Die to Wafer Stacking
- Not all sensing parameters need dedicated sensors (T, gamma)
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Gas Sensing Technologies

• XXX

| Technology | Principle | Output | |
|---|--|--|--|
| Optical detection (FTIR, NDIR, photoacoustic) | It is based on wavelength absorption of the gas: NIR to MVVIR sources are used for IR sensing; UV source is used for photo acoustic. | A shift in wavelength is measured, correlated to the target gas. | |
| Calorimetric/Pellistor | It is based on burning target gases (it is mainly for combustible gases). | A shift in temperature/resistance is measured. | |
| Electro chemical | It is based on a RedOx chemical reaction between sensor electrodes. | Current intensity is measured. | |
| Metal Oxide Semiconductor | It is mainly based on gas adsorption at the sensor surface. | A resistance change is measured. | |
| ChemFET | It is based on a change in mass/dielectric properties of a specific layer. | A change in mass/dielectric constant is measured. | |
| Acoustic | It is based on the measure of travel time of ultrasound at a given distance to calculate propagation velocity of ultrasonic waves. Concentration is linked to velocity. | Gas velocity is measured. | |
| Chromatography | Gas is electrically charged. | Output is electrical current. | |
| Chemiluminescence | Chemiluminescence (sometimes "chemoluminescence") is the emission of light (luminescence), as the result of a chemical reaction. | Output is light. | |